

ABSTRACT OF THE DISCLOSURE

A semiconductor device comprises a base frame having a first surface and a second surface which opposes the first surface, and having an opening portion a semiconductor chip
5 30 which includes a first main surface on which a plurality of electrode pads is provided and a second main surface, and which is disposed within the opening portion; an insulating film formed on the first surface and first main surface; a plurality of wiring patterns which extend from the electrode
10 pads, respectively to the upper side of the first surface of the base frame, respectively; a sealing portion formed on the wiring patterns and insulating film; and a plurality of external terminals provided on the wiring patterns in a region including the upper side of the base frame.